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Amendment to the Claims

1-7. (Cancelled)

8. (Currently Amended) A method of processing a substrate, comprising:

processing a substrate with a substrate processing liquid and then cleaning a reverse side surface of the substrate with a cleaning liquid supplied from a first reverse side nozzle connected to a first cleaning liquid supply line while circumferentially surrounding the substrate, held by a substrate holder, with a tapered portion of a scattering prevention cup, wherein the diameter of the tapered portion is progressively larger in a downward direction of the scattering prevention cup so as to ~~prevent a substrate~~ the substrate processing liquid and the cleaning liquid supplied to the substrate from being scattered around;

lowering the scattering prevention cup until an upper surface of the scattering prevention cup lies substantially on the ~~same place~~ same plane as an upper surface of the substrate held by the substrate holder so as to circumferentially surround the substrate held by the substrate holder with a smaller-diameter portion that is connected to an upper end of the tapered portion of the scattering prevention cup;

cleaning the substrate which has been processed by the processing liquid; and

horizontally supplying a cleaning liquid from a second reverse side nozzle connected to a second cleaning liquid supply line to the substrate holder in a direction toward the scattering prevention cup while rotating the substrate holder, so that the cleaning liquid from the reverse side nozzle cleans a substantially entire inner wall surface of the scattering prevention cup and an upper

surface of the substrate holder.

9-12. (Cancelled)